ABSTRACT

MANUFACTURING APPARATUS AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

A manufacturing apparatus (10) of a semiconductor device includes a stage (12), a mounting tool (20), a pressing mechanism (22), and a controller (16). The pressing mechanism (22) moves the mounting tool (20) in a vertical direction and applies a load to a chip (100). The controller (16) is configured to perform a first process and a detection process. In the first process, after bringing the chip (100) into contact and until a bump (104) melts, the chip (100) is heated by the mounting tool (20) and a command position P* of the pressing mechanism (22) is constantly updated so that a positional deviation ΔP* is constant. In the detection process, melting of the bump is detected based on a decrease in the pressing load.

Figure 1